



## PRODUCT DATA SHEET



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**Samples**

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at [www.jg-semi.cn](http://www.jg-semi.cn). Please email any questions regarding the system integration to [JINGAO\\_questions@jgsemi.com](mailto:JINGAO_questions@jgsemi.com).

## General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDSON	ID
-40V	15mΩ	-10A

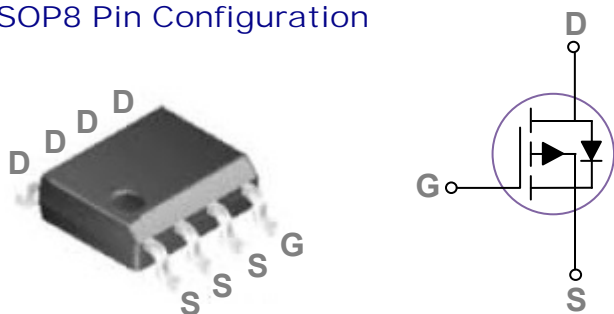
## Features

- -40V, -10A,  $R_{DS(ON)} = 15m\Omega @ V_{GS} = -10V$
- Fast switching
- Green Device Available
- Suit for -4.5V Gate Drive Applications

## Applications

- MB / VGA / Vcore
- POL Applications
- Load Switch
- LED Application

## SOP8 Pin Configuration



## Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_C=25^\circ\text{C}$ )	-10	A
	Drain Current – Continuous ( $T_C=100^\circ\text{C}$ )	-6.3	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	-40	A
$P_D$	Power Dissipation ( $T_C=25^\circ\text{C}$ )	4.2	W
	Power Dissipation – Derate above $25^\circ\text{C}$	0.034	W/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 125	$^\circ\text{C}$

## Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	30	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	---	60	$^\circ\text{C/W}$

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V$ , $I_D=-250\mu A$	-40	---	---	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-40V$ , $V_{GS}=0V$ , $T_J=25^\circ\text{C}$	---	---	-1	$\mu A$
		$V_{DS}=-32V$ , $V_{GS}=0V$ , $T_J=125^\circ\text{C}$	---	---	-10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}=0V$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-10V$ , $I_D=-10A$	---	11.5	15	$m\Omega$
		$V_{GS}=-4.5V$ , $I_D=-8A$	---	16	22	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=-250\mu A$	-1.0	-1.6	-2.5	V
$g_{fs}$	Forward Transconductance	$V_{DS}=-10V$ , $I_D=-10A$	---	13	---	S

**Dynamic and switching Characteristics**

$Q_g$	Total Gate Charge <sup>2, 3</sup>	$V_{DS}=-32V$ , $V_{GS}=-4.5V$ , $I_D=-10A$	---	22.2	40	nC
$Q_{gs}$	Gate-Source Charge <sup>2, 3</sup>		---	8.2	16	
$Q_{gd}$	Gate-Drain Charge <sup>2, 3</sup>		---	8.8	16	
$T_{d(on)}$	Turn-On Delay Time <sup>2, 3</sup>	$V_{DD}=-20V$ , $V_{GS}=-10V$ , $R_G=6\Omega$ $I_D=-1A$	---	23	40	ns
$T_r$	Rise Time <sup>2, 3</sup>		---	10	20	
$T_{d(off)}$	Turn-Off Delay Time <sup>2, 3</sup>		---	135	250	
$T_f$	Fall Time <sup>2, 3</sup>		---	46	90	
$C_{iss}$	Input Capacitance	$V_{DS}=-25V$ , $V_{GS}=0V$ , $F=1\text{MHz}$	---	2757	4000	pF
$C_{oss}$	Output Capacitance		---	240	360	
$C_{rss}$	Reverse Transfer Capacitance		---	137	200	

**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	-10	A
$I_{SM}$	Pulsed Source Current		---	---	-20	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V$ , $I_S=-1A$ , $T_J=25^\circ\text{C}$	---	---	-1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

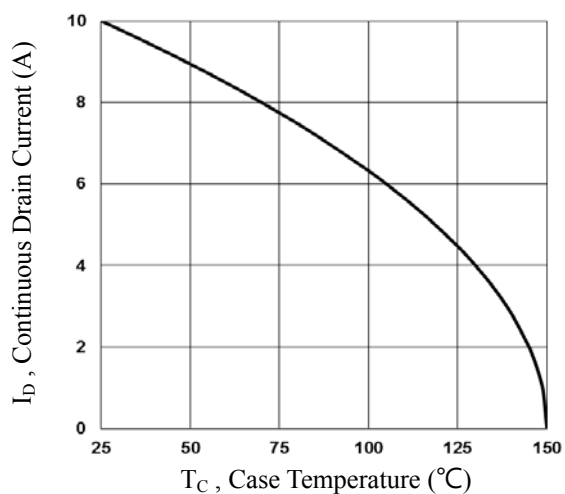


Fig.1 Continuous Drain Current vs.  $T_C$

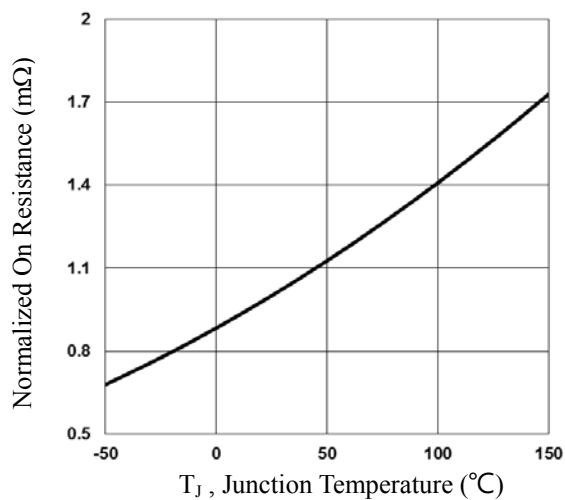


Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$

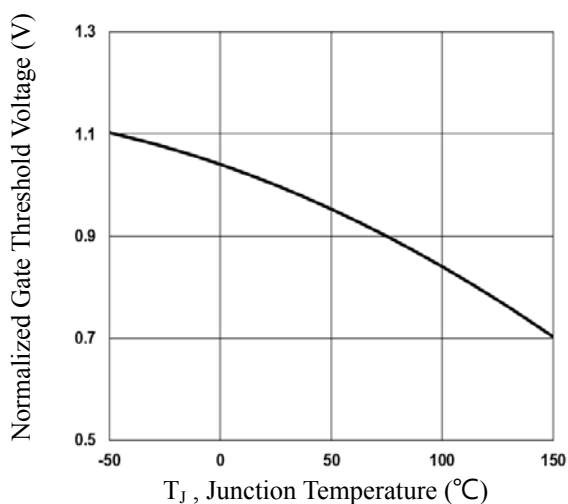


Fig.3 Normalized  $V_{th}$  vs.  $T_J$

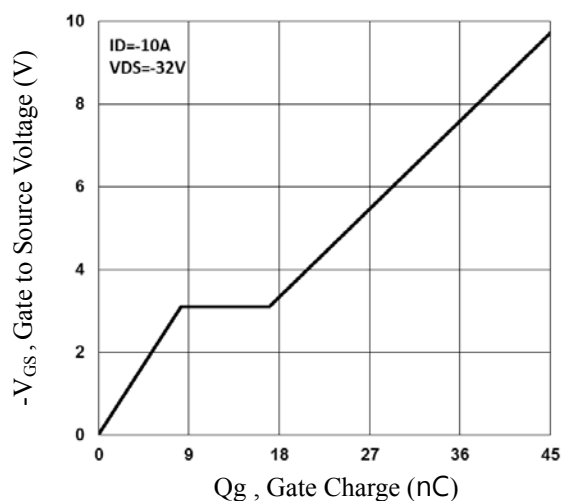


Fig.4 Gate Charge Waveform

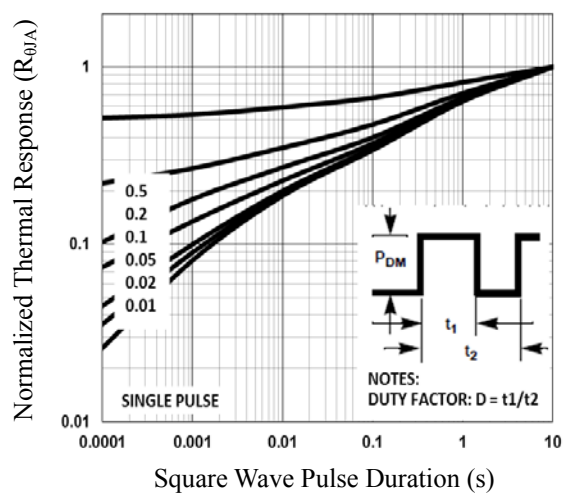


Fig.5 Normalized Transient Impedance

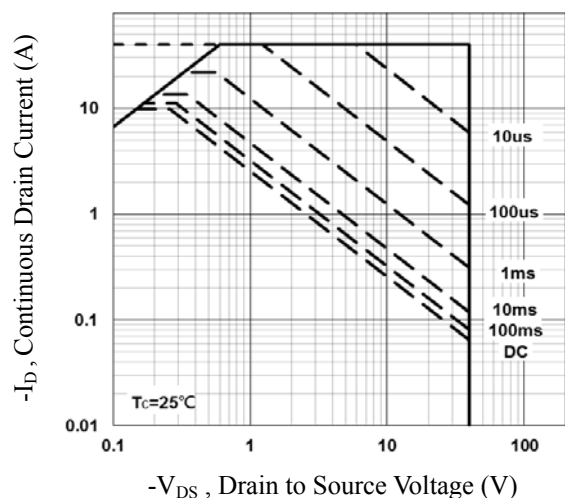


Fig.6 Maximum Safe Operation Area

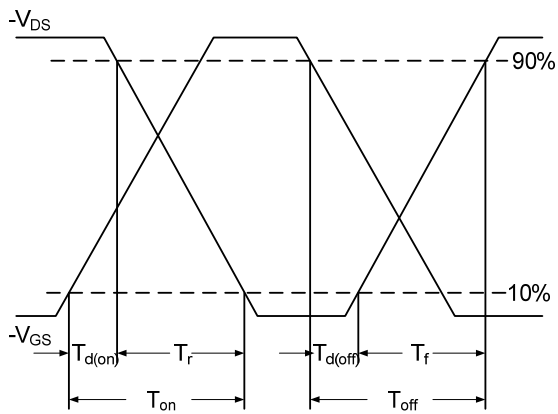


Fig.7 Switching Time Waveform

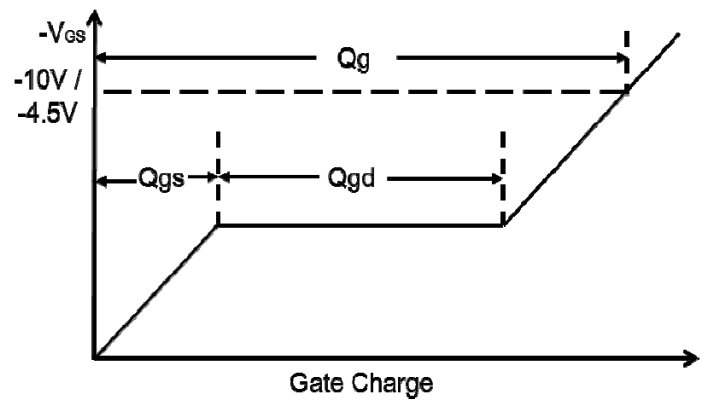
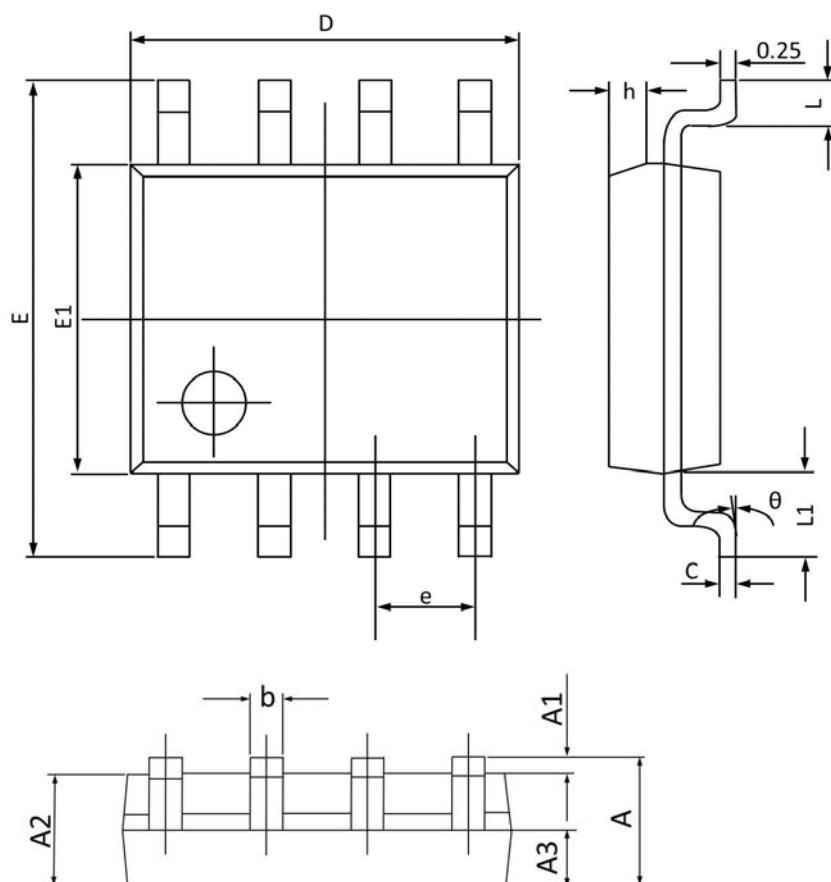


Fig.8 Gate Charge Waveform



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.068
A1	0.100	0.250	0.004	0.009
A2	1.300	1.500	0.052	0.059
A3	0.600	0.700	0.024	0.027
b	0.390	0.480	0.016	0.018
c	0.210	0.260	0.009	0.010
D	4.700	5.100	0.186	0.200
E	5.800	6.200	0.229	0.244
E1	3.700	4.100	0.146	0.161
e	1.270(BSC)		0.050(BSC)	
h	0.250	0.500	0.010	0.019
L	0.500	0.800	0.019	0.031
L1	1.050(BSC)		0.041(BSC)	
θ	0°	8°	0°	8°

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